

MATERIAL DECLARATION SHEET



Material Number	CRT0805A Series			
Product Line	Thick Film Chip Resistors			
Compliance Date	2021/06/11			
RoHS Compliant	Yes	MSL	1/2/3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Material s Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	3.81948	Aluminum oxide	1344-28-1	96%	77.86%	81.10%
				Silicon dioxide	14808-60-7	4%	3.24%	
2	Conductor Layer	Ag Alloy	0.02402	Silver	7440-22-4	95%	0.49%	0.51%
				Glass	65997-17-3	5%	0.03%	
3	Resistive Element	Ni-Cr	0.01930	Nickel	7440-02-0	45%	0.18%	0.41%
				Chromium	7440-47-3	55%	0.23%	
4	Over-Coating	Epoxy	0.21617	Epoxy	29690-82-2	100%	4.59%	4.59%
5	Over Coating	Epoxy	0.23595	Epoxy	25068-38-6	100%	5.01%	5.01%
6	Marking	Epoxy	0.00753	Epoxy	25085-99-8	100%	0.16%	0.16%
7	End Terminal	Ni-Cr	0.00565	Nickel	7440-02-0	80%	0.10%	0.12%
				Chromium	7440-47-3	20%	0.02%	
8	Ni Plating	Nickel	0.20157	Nickel	7440-02-0	100%	4.28%	4.28%
9	Sn Plating	Tin	0.17991	Tin	7440-31-5	100%	3.82%	3.82%
		Total	4.70958					

This Document was updated on: 2021/06/11

Important remarks: It is the responsibility of the user to verify they are accessing the latest version.